



DCR5960M28

Phase Control Thyristor

DS6399-1

March 2022

(LN41617)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- Crowbar
- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages VDRM and VRRM (V)	Conditions
DCR5960M28 DCR5960M26 DCR5960M24	2800 2600 2400	$T_{vj} = -40 ^{\circ} C$ to 125 $^{\circ} C$, $IDRM = IRRM = 300 mA$, $VDRM$, $VRRM$ $t_{p} = 10 ms$ $VDSM & VRSM = VDRM & VRRM + 100 V$ respectively

Lower voltage grades available.

KEY PARAMETERS

\mathbf{V}_{DRM}	2800V
I _{T(AV)}	5960A
Ітѕм	73100A
dV/dt*	2000V/μs
dl/dt	500A/μs

^{*} Higher dV/dt selections are available on request

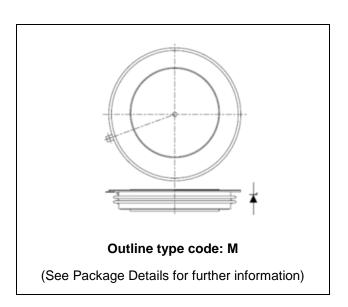


Fig. 1 Package outline

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR5960M28

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

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CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter Test Conditions		Max.	Units
Double Si	de Cooled			
IT(AV)	Mean on-state current	Half wave resistive load	5960	А
IT(RMS)	RMS value	-	9360	Α
lτ	Continuous (direct) on-state current	-	8260	Α

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, T _{case} = 125°C	73.1	kA
l²t	I ² t for fusing	V _R = 0	26.7	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Condition	Min.	Max.	Units	
		Double side cooled	DC	-	5.2	°C/kW
Rth(j-c)	Thermal resistance - junction to case	Cinale side socied	Anode DC	-	10.1	°C/kW
		Single side cooled	Cathode DC	-	10.8	°C/kW
Date 15	The word varieties a constant bacterials	Clamping force 83kN	Double side	-	1.0	°C/kW
Rth(c-h)	Thermal resistance - case to heatsink	(with mounting compound)	Single side	-	2.0	°C/kW
Tvj	Virtual junction temperature	Blocking VDRM / VRRM		-	125	°C
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force			74	91	kN

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DYNAMIC CHARACTERISTICS

Symbol	Parameter	arameter Test Conditions		Max.	Units
l===//===	Peak reverse and off-state current	At VRRM/VDRM, Tcase = 125°C		300	mA
IRRM/IDRM	Peak reverse and oir-state current	At 50% VRRM/VDRM, Tcase = 125°C	20	-	mA

Symbol	Parameter	Test Condition	ıs	Min.	Max.	Units
Vтм	Instantaneous forward voltage	At 4000A peak, Tj = 125°C		1.10	1.20	V
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V _{DRM} , Tj = 125°C, g	ate open	-	2000	V/µs
dl/dt	Data of vice of an atota augment	From 67% VDRM to 2x IT(AV)	Repetitive 50Hz	-	250	A/µs
ai/at	Rate of rise of on-state current	Gate source 30V, 10Ω tr < 0.5μ s, Tj = 125° C	Non-repetitive	-	500	A/µs
Varan	Threshold voltage - Low level	500A to 3500A at Tcase = 1	25°C	-	0.78	V
V T(TO)	Threshold voltage - High level	3500A to 9000A at Tcase = 125°C		-	0.92	V
	On-state slope resistance - Low level	500A to 3500A at Tcase = 125°C		-	0.11	mΩ
ľτ	On-state slope resistance - High level	3500A to 9000A at Tcase = 125°C		-	0.07	mΩ
tgd	Delay time	V_D = 67% V_{DRM} , gate source 30V, 10Ω t_r = 0.5μs, T_j = 25°C		-	3	μs
tq	Turn-off time	IT = 5000A, Tj = 125°C, VR = 200V, dI/dt = 5A/µs, dVpR/dt = 20V/µs linear		-	250	μs
Qs	Stored charge	I _T = 1600A, T _j = 125°C, dl/dt = 1A/μs		860	3210	μC
Irr	Reverse recovery current	$V_R \sim 1100V$, $C_S = 1\mu F$, $R_S = 63\Omega$		23	48	Α
lι	Latching current	Tj = 25°C, VD = 5V		-	3	Α
Ін	Holding current	Tj = 25°C, Rg-κ = ∞, Iτм = 50	0Α, Iτ = 5Α	-	300	mA

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GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	symbol Parameter Test Conditions		Max.	Units
V GT	Gate trigger voltage	VDRM = 5V, Tcase = 25°C	1.5	٧
V GD	Gate non-trigger voltage	At 50% VDRM, Tcase = 125°C	0.4	V
Ідт	Gate trigger current	VDRM = 5V, Tcase = 25°C	400	mA
lgp	Gate non-trigger current	At 50% VDRM, Tcase = 125°C	10	mA

CURVES

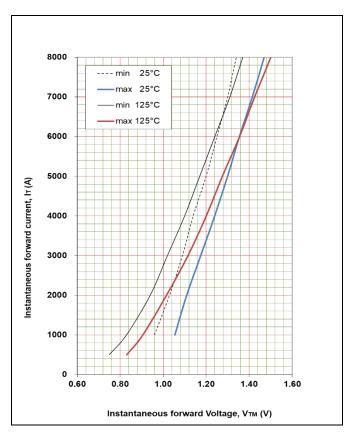


Fig. 2 Maximum & minimum on-state characteristics

VTM EQUATION

 $V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$

Where A = 0.625506

B = 0.011084

C = 0.000038

D = 0.005208

These values are valid for $T_j = 125^{\circ}C$ for I_{T} 500A to 9000A

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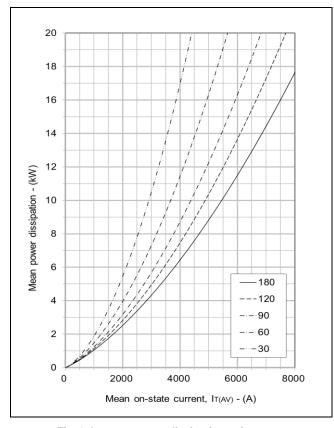


Fig. 3 On-state power dissipation - sine wave

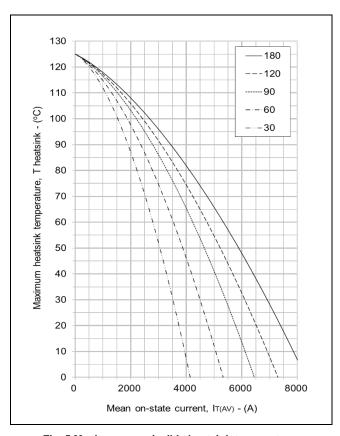


Fig. 5 Maximum permissible heatsink temperature, double side cooled - sine wave

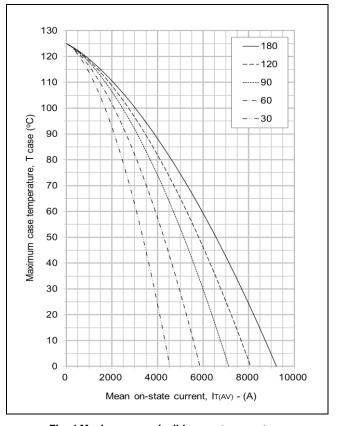


Fig. 4 Maximum permissible case temperature, double side cooled - sine wave

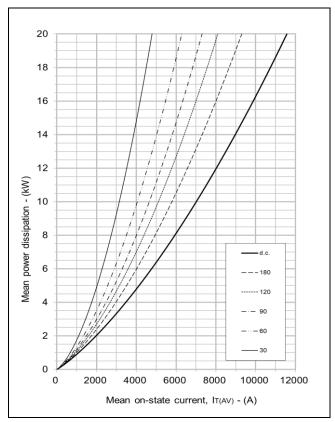


Fig. 6 On-state power dissipation - rectangular wave

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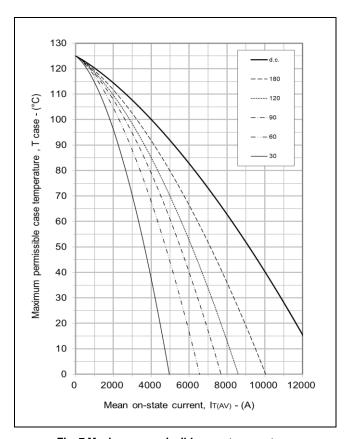
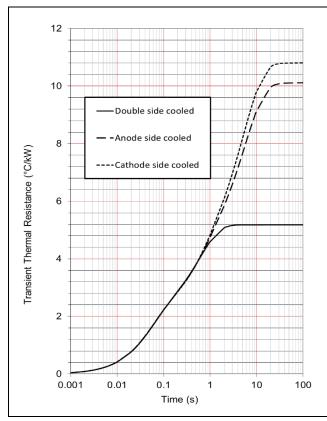


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



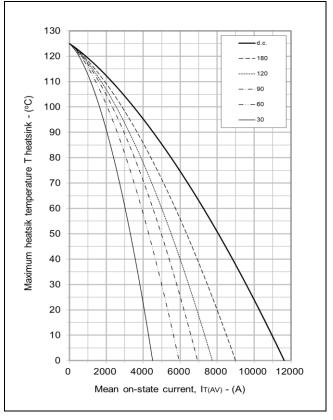


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	1.995	1.243	1.945	0.005
cooled	Ti(s)	0.050	0.593	0.592	110.511
Anode side	Ri(°C/kW)	6.093	1.957	2.042	0.036
cooled	Ti(s)	5.460	0.511	0.050	110.174
Cathode side	Ri(°C/kW)	6.857	1.876	2.063	0.025
cooled	Ti(s)	5.181	0.557	0.050	110.155

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

 $\Delta R_{\text{th(j-c)}}$ Conduction

Tables show the increments of thermal resistance R $_{\text{th}(j-c)}$ when the device operates at conduction angles other than d.c.

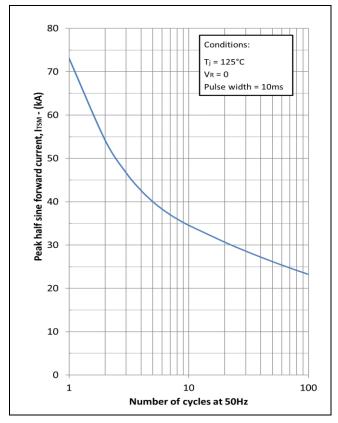
D	Double side cooling			Aı	node Side	Coolin
	ΔZ_{th} (z)				ΔZ_t	_h (Z)
θ°	sine.	rect.		θ°	sine.	rect
180	0.51	0.36		180	0.51	0.3
120	0.57	0.49		120	0.58	0.5
90	0.64	0.56		90	0.65	0.5
60	0.70	0.63		60	0.71	0.6
30	0.74	0.71		30	0.75	0.7
15	0.76	0.74	l	15	0.77	0.7

ling	Cathode Sided Cooling				
		ΔZ	th (Z)		
ect.	θ°	sine.	rect.		
.36	180	0.51	0.36		
.50	120	0.58	0.50		
).57	90	0.65	0.57		
.64	60	0.71	0.64		
.71	30	0.75	0.71		
.75	15	0.77	0.75		

Fig.9 Maximum (limit) transient thermal impedance - junction to case (degC/kW)

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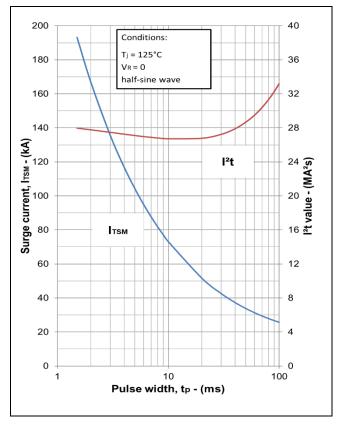


Fig. 10 Multi-cycle surge current

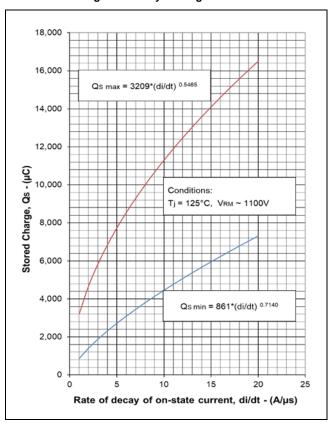


Fig. 12 Stored charge

Fig. 11 Single-cycle surge current

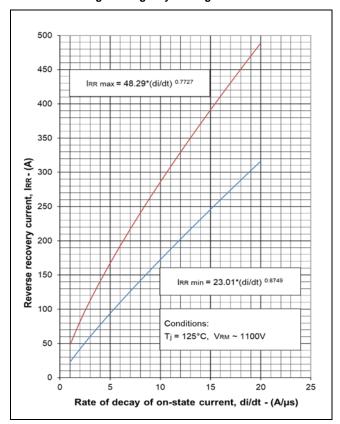


Fig. 13 Reverse recovery current

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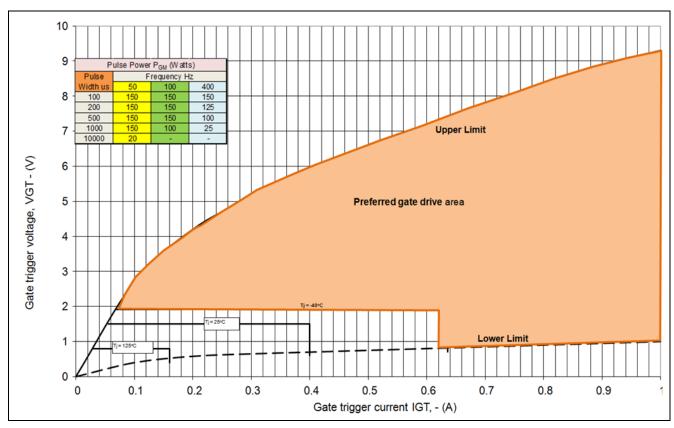


Fig.14 Gate characteristics

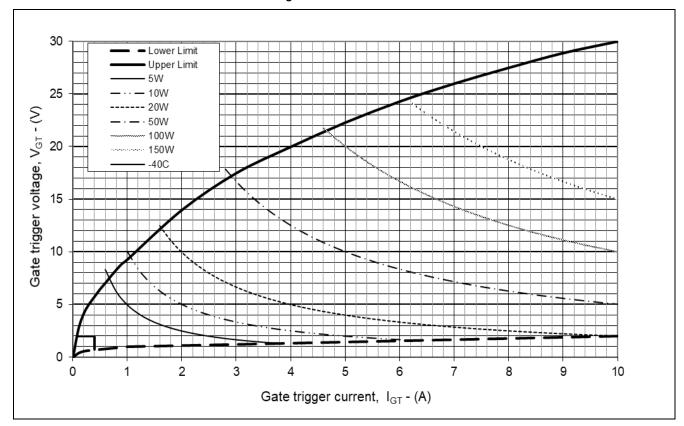


Fig. 15 Gate characteristics

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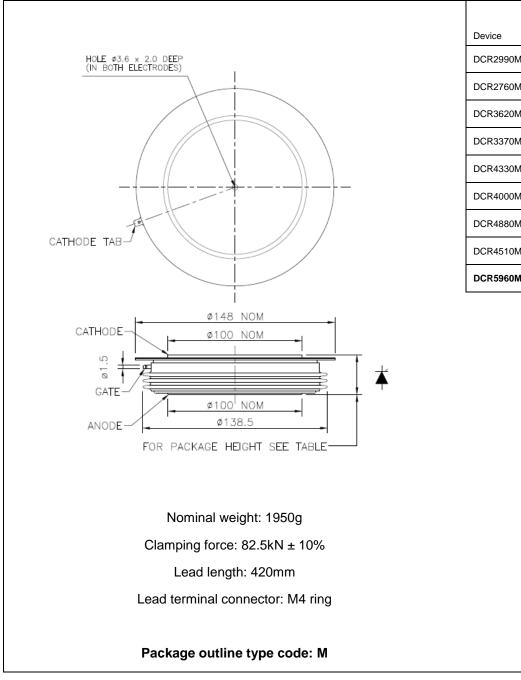


PACKAGE DETAILS

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

DO NOT SCALE



	Maximum Thickness	Minimum Thickness
Device	(mm)	(mm)
DCR2990M85	26.8	26.3
DCR2760M85	26.8	26.3
DCR3620M65	26.5	26.0
DCR3370M65	26.5	26.0
DCR4330M52	26.3	25.7
DCR4000M52	26.3	25.7
DCR4880M42	26.1	25.6
DCR4510M42	26.1	25.6
DCR5960M28	25.9	25.4

Fig. 16 Package outline

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No actual design work on the product has been started.

Provisional Information: Some initial development work has been performed. The datasheet represents a view of the

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